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**Press-Fit Standard for
Automotive Requirements and
Other High-Reliability Applications**

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An international standard developed by IPC



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**Press-Fit Standard for
Automotive Requirements
and Other High-Reliability
Applications**

Developed by the Cold Joining Press-Fit Task Group (5-21m) of
the Assembly and Joining Committee (5-20) of IPC

Users of this publication are encouraged to participate in the
development of future revisions.

Contact:

IPC
3000 Lakeside Drive, Suite 105N
Bannockburn, Illinois
60015-1249
Tel 847 615.7100
Fax 847 615.7105

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Assembly and Joining Committee	Cold Joining Press-Fit Task Group	Technical Liaison of the IPC Board of Directors
Chair Daniel Foster Missile Defense Agency	Co-Chairs Erika Crandall TE Connectivity, NC	Bob Neves Microtek (Changzou) Laboratories
Vice Chair Udo Welzel Robert Bosch GmbH	Udo Welzel Robert Bosch GmbH	
<hr/>		
Cold Joining Press-Fit Task Group		
Thomas Ahrens Trainalytics GmbH	Emma Hudson Emma Hudson Technical Consultancy Ltd	Hisao Nishimori Toyota Motor Corporation
Hideyuki Arakane Japan Unix Co., Ltd.	Frank Huijsmans PIEK International Education Centre (I.E.C.) BV	Gerry Partida Summit Interconnect - Anaheim
Bobby Bean Collins Aerospace	Philippe Jaeckle Robert Bosch GmbH	Jan Pedersen NCAB Group AB
Albert B. Block National Instruments	Bart Kerckhof TE Connectivity EC N.V.	Suraj Ramani Molex, LLC
Steve Carney Sierra Circuits Inc.	Yusaku Kono Japan Unix Co., Ltd.	Ralf-Michael Sander ebm-papst St. Georgen GmbH & Co. KG
Erika Crandall TE Connectivity, NC	Dietmar Kurzeja Possehl Electronics	Michael Schleicher Semikron Elektronik GmbH Co. KG
Clement Dehaye Alstom Transport SA (Livraison)	Francois Le-Rest Continental Automotive France SAS	Michael Schoening Q-Products-Europe
Pascal Dumontet Renault	Michael Meckl Interplex Industries, Inc	Nikhil Shinde Molex, LLC
Mark Duncan Lockheed Martin Corporation	Steve Minich Amphenol InterCon Systems	Bhanu Sood NASA Goddard Space Flight Center
Don Dupriest Lockheed Martin Missiles & Fire Control	Sohrab Moradi-Chargari Interplex Industries, Inc	Corina Stocker Continental Automotive Technologies GmbH
Hermann Eicher EPT Guglhoer GmbH	Werner MORITZ iwis smart connect GmbH	Toshiyasu Takei Japan Unix Co., Ltd.
Bernd Eifer ERNI Elektroapparate GmbH	Wolfgang Neef Kyocera AVX Components (Betzdorf) GmbH	Marius Tarnovetchi Vitesco Technologies Engineering Romania SRL
Symon Franklin Custom Interconnect Ltd	Olaf Nennewitz Mercedes-Benz AG	Juergen Turnsek Werkzeugbau Stanztechnik GmbH + Co.KG
Joachim Giuriato Molex Elektronik GmbH	Jason Nipper Collins Aerospace	
Arnaud Grivon Thales Global Services		

Frank Uibel
Uibel Consulting
Crystal E. Vanderpan
UL LLC
Jonathon Vermillion
Ball Aerospace & Technologies
Corp.

Udo Welzel
Robert Bosch GmbH
Heike Woldt
Diehl Metal Applications GmbH
Fonda B. Wu
Raytheon Company
FujiJun Wu
Toyota Motor Corporation

Robert Zauter
Wieland-Werke AG
Jack(Jian) Zhu
Veoneer China Co., Ltd
Paul Zutter
U.S. Army Aviation & Missile
Command

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Press-Fit Standard for Automotive Requirements and Other High-Reliability Applications

1 SCOPE

This standard prescribes practices for the characterization, qualification and acceptance requirements of compliant press-fit technology for printed boards that cover the manufacturability and reliability needs for high-reliability applications intended for use in harsh environments such as automotive and aerospace.

Additional requirements for aerospace applications in Appendix B may apply.

For a more complete understanding of this document's practices and requirements, one may use this document in conjunction with IPC-HDBK-9798.

1.1 Purpose This standard prescribes practices for the characterization, qualification and acceptance requirements of compliant press-fit technology for printed boards.

Standards may be updated at any time, including with the use of amendments. The use of an amendment or newer revision is not automatically required. The revision in effect **shall** be as specified by the user.

1.2 Classification

CLASS 1 General Electronic Products

Includes products suitable for applications where the major requirement is function of the completed assembly.

CLASS 2 Dedicated Service Electronic Products

Includes products where continued performance and extended life is required, and for which uninterrupted service is desired but not critical. Typically, the end-use environment would not cause failures.

CLASS 3 High Performance/Harsh Environment Electronic Products

Includes products where continued high performance or performance-on-demand is critical, equipment downtime cannot be tolerated, end-use environment may be uncommonly harsh, and the equipment must function when required, such as life support or other critical systems.

All requirements in this standard pertain to IPC Class 3. When this standard is contractually required, IPC class 3 requirements **shall** be adopted for all other contractually required standards.

1.3 Measurement Units This standard uses International System of Units (SI units) per IEEE/ASTM SI 10, Section 3 [Imperial English equivalent units are in brackets for convenience]. The SI units used in this standard are millimeters (mm) [in] for dimensions and dimensional tolerances, Celsius (°C) [°F] for temperature and temperature tolerances, grams (g) [oz] for weight, and lux (lx) [footcandles] for illuminance.

Note: This standard uses other SI prefixes (ASTM SI10, Section 3.2) to eliminate leading zeroes (for example, 0.0012 mm becomes 1.2 µm) or as an alternative to powers-of-ten (3.6 x 10³ mm becomes 3.6 m).

1.3.1 Verification of Dimensions When an inspection is done on an assembly, measuring dimensions and determining percentages listed in the standard are not required unless there is a doubt or a question is raised about the acceptance of the product. When there is a doubt or a question is raised, then a referee determination should be implemented, at which time measurements should be made or percentages calculated using the referee magnifications defined in the standard. For determining conformance to the specifications in this standard, round all observed or calculated values "to the nearest unit" in the last right-hand digit used in expressing the specification limit, in accordance with the rounding method of ASTM E29. For example, specifications of 2.5 mm max, 2.50 mm max or 2.500 mm max, round the measured value to the nearest 0.1 mm, 0.01 mm or 0.001 mm, respectively, and then compare to the specification number cited.

1.4 Definition of Requirements The words "shall" or "shall not" are used in the text of this document wherever there is a requirement for materials, preparation, process control or acceptance.